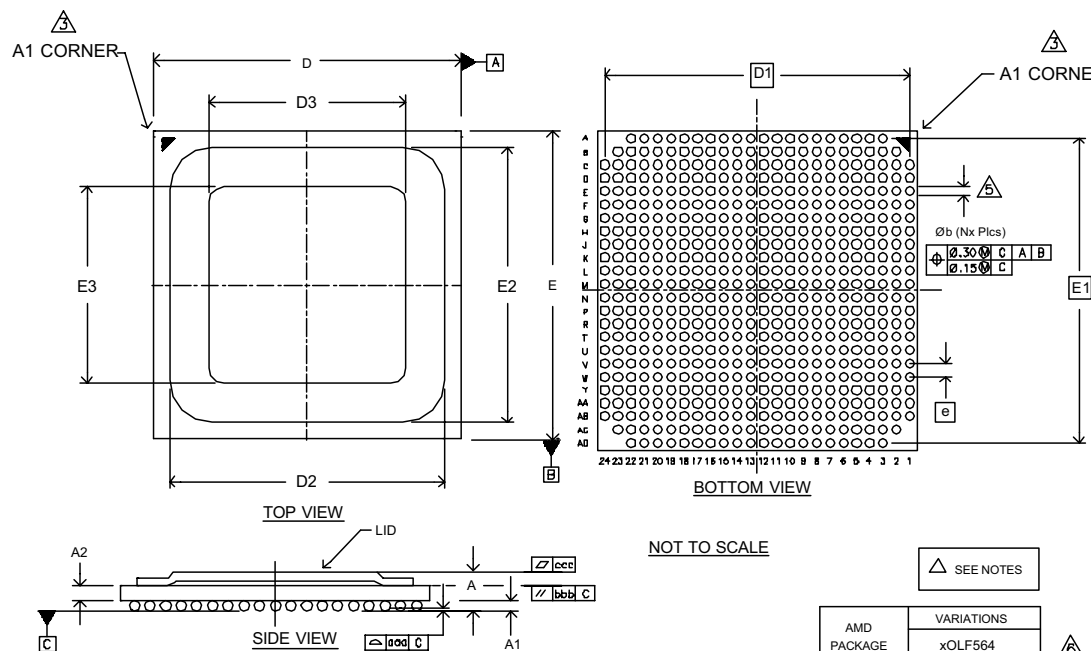


8 Package Specification



GENERAL NOTES

1. All dimensions are specified in millimeters (mm).
2. Dimensioning and tolerancing per ASME-Y14.5M-1994.
3. This corner which consists of a triangle on both sides of the package identifies ball A1 corner and can be used for handling and orientation purposes.
4. Symbol "M" determines ball matrix size and "N" is number of balls.
5. Dimension "b" is measured at maximum solder ball diameter on a plane parallel to datum C.
6. "x" in front of package variation denotes non-qualified package per AMD 01-002.3.
7. The following features are not shown on drawings:
 - a) Marking on die, label on package
 - b) Laser elements
 - c) Die and passive fudicials

AMD PACKAGE	VARIATIONS	
	xOLF564	
SYMBOL	min.	max.
D/E	30.8	31.2
D1/E1	29.21 BSC.	
D2/E2	27.8	28.2
D3/E3	22.8	23.2
A	3.25	3.56
A1	0.5	0.7
A2	0.9	1.1
e	1.27 BSC	
ϕb	0.6	0.9
M	24	
N	564	
aaa	0.2	
bbb	0.25	
ccc	0.125	

Figure 4: Package mechanical drawing.